

Product Change Notification - RMES-16BJUB395

Date: 22 Feb 2018
Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers; 32-bit PIC Microcontrollers
Notification subject: CCB 3240 Initial Notice: Qualification of TSMC (Fab 6) as an additional fabrication site in selected products of the 0.18 um wafer technology.
Notification text: **PCN Status:**
 Initial notification

PCN Type:
 Manufacturing Change

Microchip Parts Affected:
 Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
 Qualification of TSMC (Fab 6) as an additional fabrication site in selected products of the 0.18 um wafer technology.

Pre Change:
 Fabricated at TSMC (Fab 3) or TSMC (Fab 11) fabrication sites using 8 inch wafers.

Post Change:
 Fabricated at TSMC (Fab 3), TSMC (Fab 11) or TSMC (Fab 6) fabrication sites using 8 inch wafers.

Pre and Post Change Summary:

	Pre Change	Post Change	
Fab Site and Location	Taiwan Semiconductor Manufacturing Corp (TSMC) Fab 3 <i>(Hsinchu, Taiwan)</i> or Fab 11 <i>(Camas, Washington)</i>	Taiwan Semiconductor Manufacturing Corp (TSMC) Fab 3 <i>(Hsinchu, Taiwan)</i> or Fab 11 <i>(Camas, Washington)</i>	Taiwan Semiconductor Manufacturing Corp (TSMC) Fab 6 <i>(Tainan, Taiwan)</i>
Wafer Size	8 inch wafers	8 inch wafers	8 inch wafers
Quality Certification	ISO/TS16949	ISO/TS16949	ISO/TS16949
Design/Layout	No Change	No Change	No Change
Die Size	No Change	No Change	No Change

Impacts to Data Sheet:
 None

Change Impact:
 None

Reason for Change:

To improve on time delivery performance by qualifying TSMC (Fab 6) as an additional fabrication site.

Change Implementation Status:

In progress

Estimated Qualification Completion Date:

July 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2018					->	July 2018				
Workweek	5	6	7	8	9		27	28	29	30	31
Initial PCN Issue Date				X							
Qualification Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

February 22, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_RMES-16BJUB395_Qual Plan.pdf](#)
- [PCN_RMES-16BJUB395_Affected_CPN.pdf](#)
- [PCN_RMES-16BJUB395_Affected_CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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RMES-16BJUB395 - CCB 3240 Initial Notice: Qualification of TSMC (Fab 6) as an additional fabrication site in selected products of the 0.18 um wafer technology.

Affected Catalog Part Number (CPN)

PCN_RMES-16BJUB395
CATALOG_PART_NBR
DSPIC33EP128GP502-E/SS
DSPIC33EP128GP502-I/MM
DSPIC33EP128GP502-I/MMA3
DSPIC33EP128GP502-I/SO
DSPIC33EP128GP502-I/SP
DSPIC33EP128GP502-I/SS
DSPIC33EP128GP502T-I/MM
DSPIC33EP128GP504-E/ML
DSPIC33EP128GP504-E/MV
DSPIC33EP128GP504-H/ML
DSPIC33EP128GP504-H/MV
DSPIC33EP128GP504-H/PT
DSPIC33EP128GP504-I/ML
DSPIC33EP128GP504-I/MLA3
DSPIC33EP128GP504-I/MV
DSPIC33EP128GP504-I/MVA3
DSPIC33EP128GP504-I/PT
DSPIC33EP128GP504-I/TL
DSPIC33EP128GP504T-E/ML
DSPIC33EP128GP504T-E/MV
DSPIC33EP128GP504T-H/MV
DSPIC33EP128GP504T-I/ML
DSPIC33EP128GP504T-I/MV
DSPIC33EP128GP506-E/MR
DSPIC33EP128GP506-E/PT
DSPIC33EP128GP506-H/MR
DSPIC33EP128GP506-H/PT
DSPIC33EP128GP506-I/MR
DSPIC33EP128GP506-I/MRA3
DSPIC33EP128GP506-I/PT
DSPIC33EP128GP506T-I/MR
DSPIC33EP128GP506T-I/PT
DSPIC33EP128MC202-E/MM
DSPIC33EP128MC202-E/SO
DSPIC33EP128MC202-I/MM
DSPIC33EP128MC202-I/MMA3
DSPIC33EP128MC202-I/SO
DSPIC33EP128MC202-I/SP
DSPIC33EP128MC202-I/SS
DSPIC33EP128MC202T-E/MM
DSPIC33EP128MC202T-I/MM
DSPIC33EP128MC204-E/ML
DSPIC33EP128MC204-E/MV

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PCN_RMES-16BJUB395
CATALOG_PART_NBR
DSPIC33EP128MC204-E/PT
DSPIC33EP128MC204-E/TL
DSPIC33EP128MC204-H/ML
DSPIC33EP128MC204-H/MV
DSPIC33EP128MC204-H/PT
DSPIC33EP128MC204-I/ML
DSPIC33EP128MC204-I/MLA3
DSPIC33EP128MC204-I/MV
DSPIC33EP128MC204-I/MVA3
DSPIC33EP128MC204-I/PT
DSPIC33EP128MC204-I/PTA3
DSPIC33EP128MC204-I/TL
DSPIC33EP128MC204T-E/ML
DSPIC33EP128MC204T-E/MV
DSPIC33EP128MC204T-H/MV
DSPIC33EP128MC204T-I/ML
DSPIC33EP128MC204T-I/MV
DSPIC33EP128MC204T-I/PT
DSPIC33EP128MC204T-I/PTA3
DSPIC33EP128MC204T-I/TL
DSPIC33EP128MC206-E/MR
DSPIC33EP128MC206-H/MR
DSPIC33EP128MC206-H/PT
DSPIC33EP128MC206-I/MR
DSPIC33EP128MC206-I/MRA3
DSPIC33EP128MC206-I/PT
DSPIC33EP128MC206-I/PTA3
DSPIC33EP128MC206T-E/PT
DSPIC33EP128MC206T-H/MR
DSPIC33EP128MC206T-I/MR
DSPIC33EP128MC206T-I/PT
DSPIC33EP128MC206T-I/PTA3
DSPIC33EP128MC502-E/SS
DSPIC33EP128MC502-I/MM
DSPIC33EP128MC502-I/MMA3
DSPIC33EP128MC502-I/SO
DSPIC33EP128MC502-I/SP
DSPIC33EP128MC502-I/SS
DSPIC33EP128MC502T-E/MM
DSPIC33EP128MC502T-E/SS
DSPIC33EP128MC502T-I/MM
DSPIC33EP128MC504-E/ML
DSPIC33EP128MC504-E/MV

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PCN_RMES-16BJUB395
CATALOG_PART_NBR
DSPIC33EP128MC504-E/PT
DSPIC33EP128MC504-E/TL
DSPIC33EP128MC504-H/ML
DSPIC33EP128MC504-H/MV
DSPIC33EP128MC504-H/PT
DSPIC33EP128MC504-I/ML
DSPIC33EP128MC504-I/MLA3
DSPIC33EP128MC504-I/MV
DSPIC33EP128MC504-I/MVA3
DSPIC33EP128MC504-I/PT
DSPIC33EP128MC504-I/TL
DSPIC33EP128MC504-I/TLA3
DSPIC33EP128MC504T-E/ML
DSPIC33EP128MC504T-E/MV
DSPIC33EP128MC504T-H/ML
DSPIC33EP128MC504T-H/MV
DSPIC33EP128MC504T-I/ML
DSPIC33EP128MC504T-I/MV
DSPIC33EP128MC504T-I/TL
DSPIC33EP128MC506-E/MR
DSPIC33EP128MC506-E/PT
DSPIC33EP128MC506-E/PTC01
DSPIC33EP128MC506-H/MR
DSPIC33EP128MC506-H/PT
DSPIC33EP128MC506-I/MR
DSPIC33EP128MC506-I/MRA3
DSPIC33EP128MC506-I/PT
DSPIC33EP128MC506-I/PTC02
DSPIC33EP128MC506T-E/PTC01
DSPIC33EP128MC506T-I/MR
DSPIC33EP128MC506T-I/PT
DSPIC33EP128MC506T-I/PTC02
DSPIC33EP32GP502-E/MM
DSPIC33EP32GP502-E/SO
DSPIC33EP32GP502-E/SP
DSPIC33EP32GP502-E/SS
DSPIC33EP32GP502-I/MM
DSPIC33EP32GP502-I/SO
DSPIC33EP32GP502-I/SP
DSPIC33EP32GP502-I/SS
DSPIC33EP32GP502T-E/MM
DSPIC33EP32GP502T-E/SO
DSPIC33EP32GP502T-E/SS

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DSPIC33EP32GP502T-I/MM
DSPIC33EP32GP502T-I/SO
DSPIC33EP32GP502T-I/SS
DSPIC33EP32GP503-E/TL
DSPIC33EP32GP503-I/TL
DSPIC33EP32GP503T-E/TL
DSPIC33EP32GP503T-I/TL
DSPIC33EP32GP504-E/ML
DSPIC33EP32GP504-E/MV
DSPIC33EP32GP504-E/PT
DSPIC33EP32GP504-E/TL
DSPIC33EP32GP504-H/ML
DSPIC33EP32GP504-H/MV
DSPIC33EP32GP504-H/PT
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DSPIC33EP32GP504-I/MV
DSPIC33EP32GP504-I/PT
DSPIC33EP32GP504-I/TL
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DSPIC33EP32GP504T-I/MV
DSPIC33EP32GP504T-I/PT
DSPIC33EP32GP504T-I/TL
DSPIC33EP32MC202-E/MM
DSPIC33EP32MC202-E/SO
DSPIC33EP32MC202-E/SP
DSPIC33EP32MC202-E/SS
DSPIC33EP32MC202-H/SS
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DSPIC33EP32MC202-I/SO
DSPIC33EP32MC202-I/SP
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DSPIC33EP32MC202T-E/MM
DSPIC33EP32MC202T-E/SS
DSPIC33EP32MC202T-I/MM
DSPIC33EP32MC202T-I/SO
DSPIC33EP32MC202T-I/SS

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PCN_RMES-16BJUB395
CATALOG_PART_NBR
DSPIC33EP32MC202T-I/SS020
DSPIC33EP32MC203-I/TL
DSPIC33EP32MC204-E/ML
DSPIC33EP32MC204-E/MV
DSPIC33EP32MC204-E/PT
DSPIC33EP32MC204-E/PTA8
DSPIC33EP32MC204-H/ML
DSPIC33EP32MC204-H/MV
DSPIC33EP32MC204-H/PT
DSPIC33EP32MC204-I/ML
DSPIC33EP32MC204-I/MV
DSPIC33EP32MC204-I/PT
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DSPIC33EP32MC504-I/PT

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CATALOG_PART_NBR
DSPIC33EP32MC504-I/TL
DSPIC33EP32MC504T-E/ML
DSPIC33EP32MC504T-E/MV
DSPIC33EP32MC504T-H/ML
DSPIC33EP32MC504T-H/MV
DSPIC33EP32MC504T-H/PT
DSPIC33EP32MC504T-I/ML
DSPIC33EP32MC504T-I/MV
DSPIC33EP32MC504T-I/PT
DSPIC33EP32MC504T-I/TL
DSPIC33EP64GP502-E/MM
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DSPIC33EP64GP502-E/SP
DSPIC33EP64GP502-E/SS
DSPIC33EP64GP502-H/MM
DSPIC33EP64GP502-I/MM
DSPIC33EP64GP502-I/MMA3
DSPIC33EP64GP502-I/SO
DSPIC33EP64GP502-I/SP
DSPIC33EP64GP502-I/SS
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DSPIC33EP64GP504-H/ML
DSPIC33EP64GP504-H/MV
DSPIC33EP64GP504-I/ML
DSPIC33EP64GP504-I/MLA3
DSPIC33EP64GP504-I/MV
DSPIC33EP64GP504-I/MVA3
DSPIC33EP64GP504-I/PT
DSPIC33EP64GP504-I/PTA3
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DSPIC33EP64GP504T-H/ML
DSPIC33EP64GP504T-H/MV
DSPIC33EP64GP504T-I/ML

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PCN_RMES-16BJUB395
CATALOG_PART_NBR
DSPIC33EP64GP504T-I/MV
DSPIC33EP64GP506-E/MR
DSPIC33EP64GP506-E/PT
DSPIC33EP64GP506-H/MR
DSPIC33EP64GP506-I/MR
DSPIC33EP64GP506-I/MRA3
DSPIC33EP64GP506-I/PT
DSPIC33EP64GP506-I/PTA3
DSPIC33EP64GP506T-E/MR
DSPIC33EP64GP506T-H/MR
DSPIC33EP64GP506T-I/MR
DSPIC33EP64MC202-E/MM
DSPIC33EP64MC202-E/SO
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DSPIC33EP64MC202-E/SS
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DSPIC33EP64MC202-I/MM
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DSPIC33EP64MC204-I/MV
DSPIC33EP64MC204-I/PT
DSPIC33EP64MC204-I/PTC02
DSPIC33EP64MC204-I/TL

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PCN_RMES-16BJUB395
CATALOG_PART_NBR
DSPIC33EP64MC204T-E/ML
DSPIC33EP64MC204T-E/MV
DSPIC33EP64MC204T-E/PT
DSPIC33EP64MC204T-E/TL
DSPIC33EP64MC204T-H/ML
DSPIC33EP64MC204T-H/MV
DSPIC33EP64MC204T-H/PT
DSPIC33EP64MC204T-I/ML
DSPIC33EP64MC204T-I/MV
DSPIC33EP64MC204T-I/PT
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DSPIC33EP64MC206-E/MR
DSPIC33EP64MC206-E/PT
DSPIC33EP64MC206-E/PTA8
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DSPIC33EP64MC206-I/PTA3
DSPIC33EP64MC206T-E/MR
DSPIC33EP64MC206T-E/MRC04
DSPIC33EP64MC206T-E/PT
DSPIC33EP64MC206T-E/PTA8
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DSPIC33EP64MC206T-H/PT
DSPIC33EP64MC206T-I/MR
DSPIC33EP64MC206T-I/PT
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DSPIC33EP64MC502-I/SS
DSPIC33EP64MC502T-E/MM
DSPIC33EP64MC502T-E/SO
DSPIC33EP64MC502T-E/SS
DSPIC33EP64MC502T-H/MM

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CATALOG_PART_NBR
DSPIC33EP64MC502T-I/MM
DSPIC33EP64MC502T-I/SO
DSPIC33EP64MC502T-I/SS
DSPIC33EP64MC503-E/TL
DSPIC33EP64MC503-I/TL
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DSPIC33EP64MC506T-I/MR
DSPIC33EP64MC506T-I/PT
HA1044-I/PT
HA4583-I/PT
HA4583T-I/PT
HA4584-I/PT
HA4584T-I/PT
PIC24EP128GP202-E/MM

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Affected Catalog Part Number (CPN)

PCN_RMES-16BJUB395
CATALOG_PART_NBR
PIC24EP128GP202-I/MM
PIC24EP128GP202-I/MMA3
PIC24EP128GP202-I/SO
PIC24EP128GP202-I/SP
PIC24EP128GP202-I/SS
PIC24EP128GP202T-E/SS
PIC24EP128GP202T-I/MM
PIC24EP128GP204-E/ML
PIC24EP128GP204-E/MV
PIC24EP128GP204-E/PT
PIC24EP128GP204-H/ML
PIC24EP128GP204-H/MV
PIC24EP128GP204-H/PT
PIC24EP128GP204-I/ML
PIC24EP128GP204-I/MLA3
PIC24EP128GP204-I/MV
PIC24EP128GP204-I/MV029
PIC24EP128GP204-I/MVA3
PIC24EP128GP204-I/PT
PIC24EP128GP204-I/PT030
PIC24EP128GP204-I/PT035
PIC24EP128GP204-I/PT037
PIC24EP128GP204-I/TL
PIC24EP128GP204T-E/MV
PIC24EP128GP204T-H/MV
PIC24EP128GP204T-I/ML
PIC24EP128GP204T-I/MV
PIC24EP128GP204T-I/MV029
PIC24EP128GP204T-I/PT
PIC24EP128GP204T-I/PT030
PIC24EP128GP204T-I/PT032
PIC24EP128GP204T-I/PT033
PIC24EP128GP204T-I/PT035
PIC24EP128GP204T-I/PT037
PIC24EP128GP206-E/MR
PIC24EP128GP206-H/MR
PIC24EP128GP206-H/PT
PIC24EP128GP206-I/MR
PIC24EP128GP206-I/MRA3
PIC24EP128GP206-I/PT
PIC24EP128GP206T-I/MR
PIC24EP128GP206T-I/PT
PIC24EP128MC202-I/MM

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Affected Catalog Part Number (CPN)

PCN_RMES-16BJUB395
CATALOG_PART_NBR
PIC24EP128MC202-I/MMA3
PIC24EP128MC202-I/SO
PIC24EP128MC202-I/SP
PIC24EP128MC202-I/SS
PIC24EP128MC202T-I/MM
PIC24EP128MC204-E/ML
PIC24EP128MC204-E/MV
PIC24EP128MC204-H/ML
PIC24EP128MC204-H/MV
PIC24EP128MC204-H/PT
PIC24EP128MC204-I/ML
PIC24EP128MC204-I/MLA3
PIC24EP128MC204-I/MV
PIC24EP128MC204-I/MVA3
PIC24EP128MC204-I/PT
PIC24EP128MC204-I/TL
PIC24EP128MC204T-E/MV
PIC24EP128MC204T-H/MV
PIC24EP128MC204T-I/ML
PIC24EP128MC204T-I/MV
PIC24EP128MC206-E/MR
PIC24EP128MC206-H/MR
PIC24EP128MC206-H/PT
PIC24EP128MC206-I/MR
PIC24EP128MC206-I/MRA3
PIC24EP128MC206-I/PT
PIC24EP128MC206T-I/MR
PIC24EP32GP202-E/MM
PIC24EP32GP202-E/SO
PIC24EP32GP202-E/SP
PIC24EP32GP202-E/SS
PIC24EP32GP202-I/MM
PIC24EP32GP202-I/SO
PIC24EP32GP202-I/SP
PIC24EP32GP202-I/SS
PIC24EP32GP202T-E/MM
PIC24EP32GP202T-E/SO
PIC24EP32GP202T-E/SS
PIC24EP32GP202T-I/MM
PIC24EP32GP202T-I/SO
PIC24EP32GP202T-I/SS
PIC24EP32GP203-E/TL
PIC24EP32GP203-I/TL

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Affected Catalog Part Number (CPN)

PCN_RMES-16BJUB395
CATALOG_PART_NBR
PIC24EP32GP203T-E/TL
PIC24EP32GP203T-I/TL
PIC24EP32GP204-E/ML
PIC24EP32GP204-E/MV
PIC24EP32GP204-E/PT
PIC24EP32GP204-E/TL
PIC24EP32GP204-H/ML
PIC24EP32GP204-H/MV
PIC24EP32GP204-H/PT
PIC24EP32GP204-I/ML
PIC24EP32GP204-I/MV
PIC24EP32GP204-I/PT
PIC24EP32GP204-I/TL
PIC24EP32GP204T-E/ML
PIC24EP32GP204T-E/MV
PIC24EP32GP204T-E/PT
PIC24EP32GP204T-E/TL
PIC24EP32GP204T-H/ML
PIC24EP32GP204T-H/MV
PIC24EP32GP204T-H/PT
PIC24EP32GP204T-I/ML
PIC24EP32GP204T-I/MV
PIC24EP32GP204T-I/PT
PIC24EP32GP204T-I/TL
PIC24EP32MC202-E/MM
PIC24EP32MC202-E/SO
PIC24EP32MC202-E/SP
PIC24EP32MC202-E/SS
PIC24EP32MC202-I/MM
PIC24EP32MC202-I/SO
PIC24EP32MC202-I/SP
PIC24EP32MC202-I/SS
PIC24EP32MC202T-E/MM
PIC24EP32MC202T-E/SS
PIC24EP32MC202T-I/MM
PIC24EP32MC204-E/ML
PIC24EP32MC204-E/MV
PIC24EP32MC204-H/ML
PIC24EP32MC204-H/MV
PIC24EP32MC204-H/PT
PIC24EP32MC204-I/ML
PIC24EP32MC204-I/MV
PIC24EP32MC204-I/PT

RMES-16BJUB395 - CCB 3240 Initial Notice: Qualification of TSMC (Fab 6) as an additional fabrication site in selected products of the 0.18 um wafer technology.

Affected Catalog Part Number (CPN)

PCN_RMES-16BJUB395
CATALOG_PART_NBR
PIC24EP32MC204-I/TL
PIC24EP32MC204T-E/ML
PIC24EP32MC204T-E/MV
PIC24EP32MC204T-H/ML
PIC24EP32MC204T-H/MV
PIC24EP32MC204T-H/PT
PIC24EP32MC204T-I/ML
PIC24EP32MC204T-I/MV
PIC24EP64GP202-E/MM
PIC24EP64GP202-E/SO
PIC24EP64GP202-H/MM
PIC24EP64GP202-I/MM
PIC24EP64GP202-I/MMA3
PIC24EP64GP202-I/SO
PIC24EP64GP202-I/SP
PIC24EP64GP202-I/SS
PIC24EP64GP202T-E/MM
PIC24EP64GP202T-H/MM
PIC24EP64GP202T-I/MM
PIC24EP64GP202T-I/SS
PIC24EP64GP203-I/TL
PIC24EP64GP204-E/ML
PIC24EP64GP204-E/MV
PIC24EP64GP204-E/PT
PIC24EP64GP204-H/ML
PIC24EP64GP204-H/MV
PIC24EP64GP204-I/ML
PIC24EP64GP204-I/MLA3
PIC24EP64GP204-I/MV
PIC24EP64GP204-I/MVA3
PIC24EP64GP204-I/PT
PIC24EP64GP204-I/PTA3
PIC24EP64GP204-I/PTC03
PIC24EP64GP204T-E/ML
PIC24EP64GP204T-E/MV
PIC24EP64GP204T-H/ML
PIC24EP64GP204T-H/MV
PIC24EP64GP204T-I/ML
PIC24EP64GP204T-I/MV
PIC24EP64GP204T-I/PT
PIC24EP64GP206-E/MR
PIC24EP64GP206-E/PT
PIC24EP64GP206-H/MR

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Affected Catalog Part Number (CPN)

PCN_RMES-16BJUB395
CATALOG_PART_NBR
PIC24EP64GP206-I/MR
PIC24EP64GP206-I/MRA3
PIC24EP64GP206-I/PT
PIC24EP64GP206-I/PTA3
PIC24EP64GP206T-E/MR
PIC24EP64GP206T-H/MR
PIC24EP64GP206T-I/MR
PIC24EP64MC202-E/MM
PIC24EP64MC202-E/SO
PIC24EP64MC202-E/SP
PIC24EP64MC202-E/SS
PIC24EP64MC202-H/MM
PIC24EP64MC202-I/MM
PIC24EP64MC202-I/SO
PIC24EP64MC202-I/SP
PIC24EP64MC202-I/SS
PIC24EP64MC202T-E/MM
PIC24EP64MC202T-E/SO
PIC24EP64MC202T-E/SS
PIC24EP64MC202T-H/MM
PIC24EP64MC202T-I/MM
PIC24EP64MC202T-I/SO
PIC24EP64MC202T-I/SS
PIC24EP64MC203-E/TL
PIC24EP64MC203-I/TL
PIC24EP64MC203T-I/TL
PIC24EP64MC204-E/ML
PIC24EP64MC204-E/MV
PIC24EP64MC204-E/PT
PIC24EP64MC204-E/TL
PIC24EP64MC204-H/ML
PIC24EP64MC204-H/MV
PIC24EP64MC204-I/ML
PIC24EP64MC204-I/MV
PIC24EP64MC204-I/PT
PIC24EP64MC204-I/PTC06
PIC24EP64MC204-I/TL
PIC24EP64MC204T-E/ML
PIC24EP64MC204T-E/MV
PIC24EP64MC204T-E/PT
PIC24EP64MC204T-E/TL
PIC24EP64MC204T-H/ML
PIC24EP64MC204T-H/MV

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Affected Catalog Part Number (CPN)

PCN_RMES-16BJUB395
CATALOG_PART_NBR
PIC24EP64MC204T-I/ML
PIC24EP64MC204T-I/MV
PIC24EP64MC204T-I/PT
PIC24EP64MC204T-I/TL
PIC24EP64MC206-E/MR
PIC24EP64MC206-E/PT
PIC24EP64MC206-H/MR
PIC24EP64MC206-I/MR
PIC24EP64MC206-I/PT
PIC24EP64MC206T-E/MR
PIC24EP64MC206T-E/PT
PIC24EP64MC206T-H/MR
PIC24EP64MC206T-I/MR
PIC24EP64MC206T-I/PT
DSPIC33EP128GP504-E/PTVAO
DSPIC33EP128GP504T-E/PTVAO
DSPIC33EP128MC202T-E/MMVAO
DSPIC33EP128MC206T-H/MRVAO
DSPIC33EP128MC504-E/PTVAO
DSPIC33EP128MC504-H/PTVAO
DSPIC33EP128MC504T-E/PTVAO
DSPIC33EP128MC504T-H/PTVAO
DSPIC33EP128MC506-E/PTVAO
DSPIC33EP128MC506T-E/PTVAO
DSPIC33EP128MC506T-H/PTVAO
DSPIC33EP32GP502-E/MMVAO
DSPIC33EP32GP502-E/SSVAO
DSPIC33EP32GP502-I/SSVAO
DSPIC33EP32GP502T-E/MMVAO
DSPIC33EP32GP502T-E/SSVAO
DSPIC33EP32GP502T-I/SSVAO
DSPIC33EP32MC202-E/SSVAO
DSPIC33EP32MC202-H/MMVAO
DSPIC33EP32MC202T-E/SSVAO
DSPIC33EP32MC202T-H/MMVAO
DSPIC33EP32MC204-E/PTVAO
DSPIC33EP32MC204-H/MLVAO
DSPIC33EP32MC204T-E/PTVAO
DSPIC33EP32MC204T-H/MLVAO
DSPIC33EP32MC502-E/SSVAO
DSPIC33EP32MC502T-E/SSVAO
DSPIC33EP32MC504-E/PTVAO
DSPIC33EP64GP502-E/SSVAO

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Affected Catalog Part Number (CPN)

PCN_RMES-16BJUB395
CATALOG_PART_NBR
DSPIC33EP64GP502T-E/SSVAO
DSPIC33EP64GP504-I/PTVAO
DSPIC33EP64GP504T-I/PTVAO
DSPIC33EP64GP506-I/PTVAO
DSPIC33EP64MC204-E/PTVAO
DSPIC33EP64MC204-H/MLVAO
DSPIC33EP64MC204T-E/PTVAO
DSPIC33EP64MC204T-H/MLVAO
DSPIC33EP64MC504-E/PTVAO
DSPIC33EP64MC504T-E/PTVAO
DSPIC33EP64MC506-E/PTVAO
DSPIC33EP64MC506T-E/PTVAO
DSPIC33EP64MC506T-H/PTVAO
PIC24EP128GP204-E/PTVAO
PIC24EP128GP204T-E/PTVAO
PIC24EP128GP206-I/PTVAO
PIC24EP128GP206T-I/PTVAO